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Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Wicrosemi POWER PRODUCTS GROUP

1200V, 70A, $V_{ce(on)}$ = 2.5V Typical

Ultra Fast NPT - IGBT®

The Ultra Fast NPT - IGBT[®] is a new generation of high voltage power IGBTs. Using Non-Punch-Through Technology, the Ultra Fast NPT-IGBT[®] offers superior ruggedness and ultrafast switching speed.

Features

- Low Saturation Voltage
- Low Tail Current
- RoHS Compliant *M*

- Short Circuit Withstand Rated
- High Frequency Switching
- Ultra Low Leakage Current

Unless stated otherwise, Microsemi discrete IGBTs contain a single IGBT die. This device is recommended for applications such as induction heating (IH), motor control, general purpose inverters and uninterruptible power supplies (UPS).

MAXIMUM RATINGS

All Ratings: $T_{C} = 25^{\circ}C$ unless otherwise specified.

Symbol	Parameter	Ratings	Unit
V _{ces}	Collector Emitter Voltage	1200	V
V _{GE}	Gate-Emitter Voltage	±30	v
I _{C1}	Continuous Collector Current @ T _c = 25°C	112	Î
I _{C2}	Continuous Collector Current @ T _c = 86°C	70	A
I _{CM}	Pulsed Collector Current ①	280	
SCWT	Short Circuit Withstand Time: V_{CE} = 600V, V_{GE} = 15V, T_{C} =125°C	10	μs
P _D	Total Power Dissipation @ $T_c = 25^{\circ}C$	543	W
T _J ,T _{STG}	Operating and Storage Junction Temperature Range	-55 to 150	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Min	Тур	Max	Unit
V _{(BR)CES}	Collector-Emitter Breakdown Voltage ($V_{GE} = 0V$, $I_{C} = 1.0$ mA)	1200			
V _{GE(TH)}	Gate Threshold Voltage ($V_{CE} = V_{GE}$, $I_{C} = 2.5$ mA, $T_{j} = 25^{\circ}$ C)	3.5	5.0	6.5	Volts
V _{CE(ON)}	Collector-Emitter On Voltage (V_{GE} = 15V, I_{c} = 70A, T_{j} = 25°C)		2.5	3.2	
	Collector-Emitter On Voltage (V_{GE} = 15V, I_{c} = 70A, T_{j} = 125°C)		3.3		
	Collector-Emitter On Voltage (V_{GE} = 15V, I _c = 140A, T _j = 25°C)		3.5		
I _{CES}	Collector Cut-off Current (V _{CE} = 1200V, V _{GE} = 0V, T _j = 25°C) ⁽²⁾		10	1000	μA
	Collector Cut-off Current (V _{CE} = 1200V, V _{GE} = 0V, T _j = 125°C) ⁽²⁾		100		
I _{GES}	Gate-Emitter Leakage Current (V _{GE} = ±20V)			±250	nA

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.





DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditions	Min	Тур	Мах	Unit
C _{ies}	Input Capacitance	Capacitance		7260		
C _{oes}	Output Capacitance	$V_{GE} = 0V, V_{CE} = 25V$		643		pF
C _{res}	Reverse Transfer Capacitance	f = 1MHz		199		
V _{GEP}	Gate to Emitter Plateau Voltage	Cata Charra		7.5		V
Q _g ③	Total Gate Charge			412	544	
Q _{ge}	Gate-Emitter Charge	$V_{GE} = 15V$		48	62	
Q _{gc}	Gate- Collector Charge	V _{CE} = 800V I _C = 70A		204	275	nC
t _{d(on)}	Turn-On Delay Time	Inductive Switching (25°C)		33		
t,	Current Rise Time	$V_{cc} = 600V$		48		
t _{d(off)}	Turn-Off Delay Time	V _{GE} = 15V		278		ns
t _r	Current Fall Time	I _c = 70A		64		
E _{on2} 5	Turn-On Switching Energy	$R_{g} = 4.3 \ \Omega^{(4)}$		3816	5720	
E _{off}	Turn-Off Switching Energy	T _J = +25°C		2582	3870	μJ
t _{d(on)}	Turn-On Delay Time	Inductive Switching (125°C)		33		
t,	Current Rise Time	$V_{cc} = 600V$		48		
t _{d(off)}	Turn-Off Delay Time	V _{GE} = 15V		320		ns
t _r	Current Fall Time	I _c = 70A		74		
E _{on2} 5	Turn-On Switching Energy	$R_{g} = 4.3 \ \Omega^{(4)}$		5651	8475	1
E _{off}	Turn-Off Switching Energy	T _J = +125°C		3323	4980	μJ

THERMAL AND MECHANICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	Min	Тур	Max	Unit
R _{ejc}	Junction to Case	-	-	0.23	°C/W
W _T	Package Weight	-	1.03	-	oz
Torque	Terminals and Mounting Screws.	-	-	10	in∙lbf
		-	-	1.1	N∙m
V _{Isolation}	RMS Voltage (50-60Hz Sinusoidal Waveform from Terminals to Mounting Base for 1 Min.)	2500	-	-	Volts

1 Repetitive Rating: Pulse width and case temperature limited by maximum junction temperature.

2 Pulse test: Pulse Width < 380µs, duty cycle < 2%.

3 See Mil-Std-750 Method 3471.

4 R_g is external gate resistance, not including internal gate resistance or gate driver impedance. (MIC4452)

5 E_{on2} is the clamped inductive turn on energy that includes a commutating diode reverse recovery current in the IGBT turn on energy loss. A combi device is used for the clamping diode.

6 E is the clamped inductive turn-off energy measured in accordance with JEDEC standard JESD24-1. Microsemi reserves the right to change, without notice, the specifications and information contained herein.



RECTANGULAR PULSE DURATION (SECONDS) Figure 1, Maximum Effective Transient Thermal Impedance, Junction-To-Case vs Pulse Duration

TYPICAL PERFORMANCE CURVES











SOT-227 (ISOTOP®) Package Outline

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